



# Product End-of-Life Disassembly Instructions

**Product Category: Monitors and Displays**

**Marketing Name / Model**  
**[List multiple models if applicable.]**

HP ZR22w LCD Monitor

Name / Model #2

Name / Model #3

Name / Model #4

Name / Model #5

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	4
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	2
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		5
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0

Components, parts and materials containing radioactive substances		0
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## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 SCREW DRIVER(PHILLIPS HEAD)	#2
Description #2	
Description #3	
Description #4	
Description #5	

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Stand Base From Display Head
2. Remove Rear Cover From Display Head
3. Remove Front Cover From Display Head
4. Remove Key Board Off From Front Cover
5. Remove Trim Cover From Rear Cover
6. Take Screw(\*2) Off From Chassis Cover & Remove Panel
7. Take Screw(x8) Off From P.C.B
8. Take Screw(x7) Off From P.C.B
9. Take Screw(x8) Off From P.C.B & Remove BKT (Printed Circuit Assemblies>10cm\*\*2)
10. Remove Mylar From Chassis Cover
11. LCD PANEL EXPLODE
12. Take Screw(\*4)Off From Quick Release
13. Remove Quick Release off Stand Base
14. EXPLODE Quick Release
15. Remove Cable Cover Off Stand Base
16. Remove Stand Front Cover Off Stand Base
17. Remove Stand Rear Cover Off Stand Base
18. Remove Stand Columnb Rear off Stand Base
19. Remove Stand Columnb Front Off Stand BKT
20. Remove Vesa Cover Assy Off Stand BKT
21. Remove Vesa Cover Off VESA BKT
22. Remove Pivot Cover Off Swivel
23. Remove Tilt Cover and Stand Columnb Top Off Stand BKT
24. Remove Rubber Off Base BKT
25. Remove Base Off Base BKT
26. Remove Release Button Off Stand Rear Cover

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

# HP ZR22w Disassembly Process

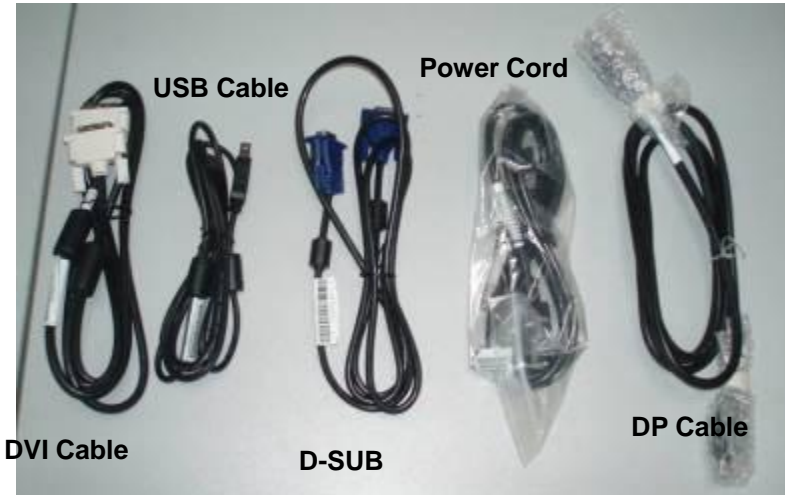
- Jeremy Zhang
- Mechanical Engineer
- Nov-10-2009



# External Electric Cables Dissecting Process

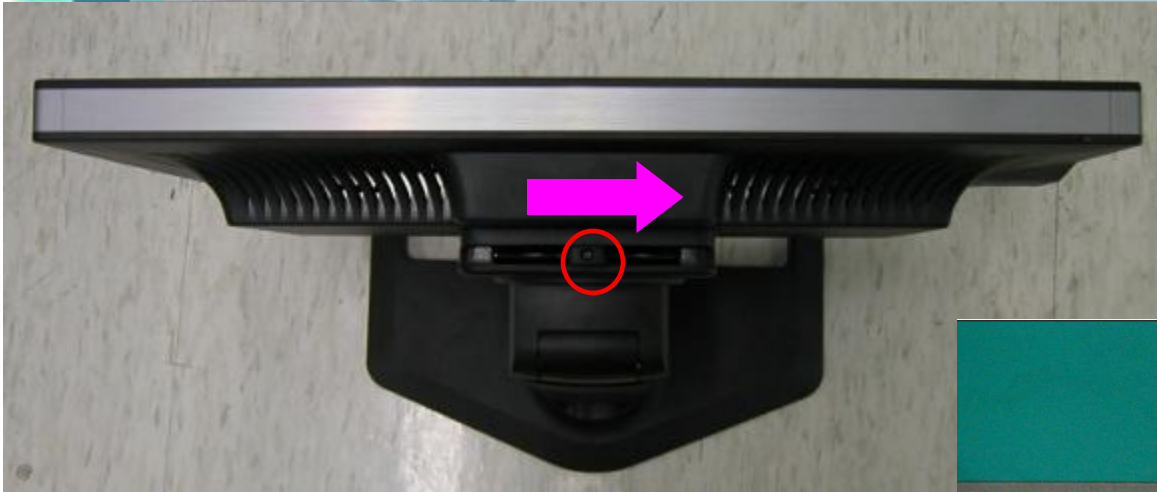


1.Remove Cable From Display Head.



2.Dissecting To Complete.

## ▶ Remove Stand Base From Display Head



1. Rotate the Quick release button



2. Remove Stand Base From Display Head.

## ▶ Remove Stand Base From Display Head



3.Remove 4 pcs screws.



4.Remove Quick Release Metal.



# Remove Rear Cover From Display Head



5.Remove Rear Cover From Display Head.

# ▶ Remove Front Cover From Display Head

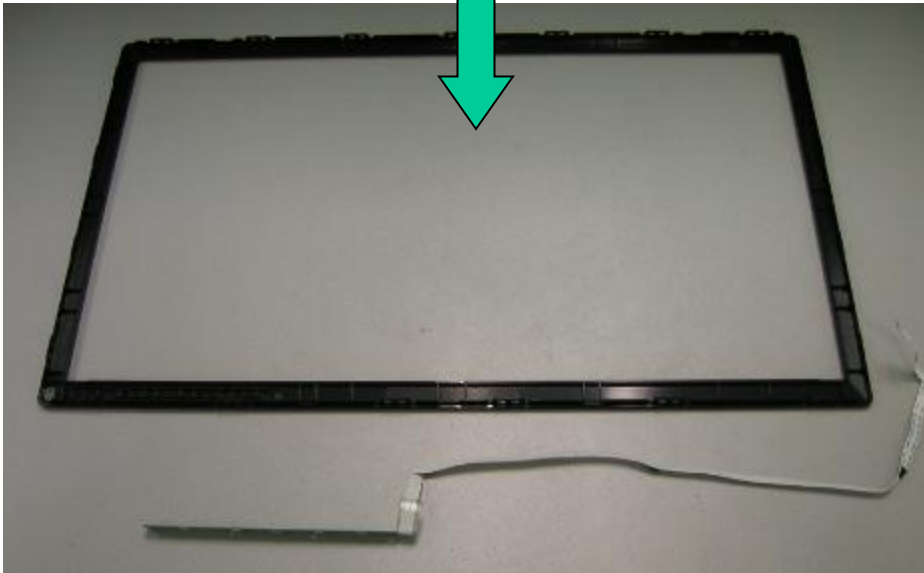
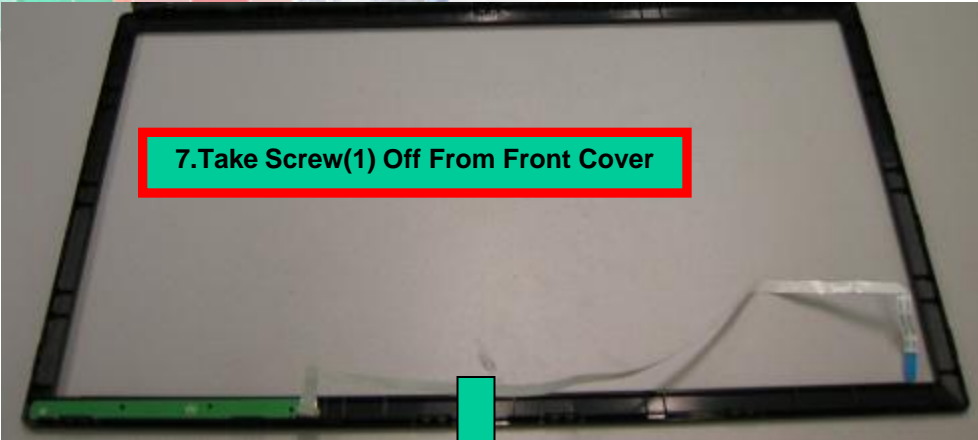


6.Remove Front Cover.



## ▶ Remove Key Board Off From Front Cover

7. Take Screw(1) Off From Front Cover



8. Remove key board from FC

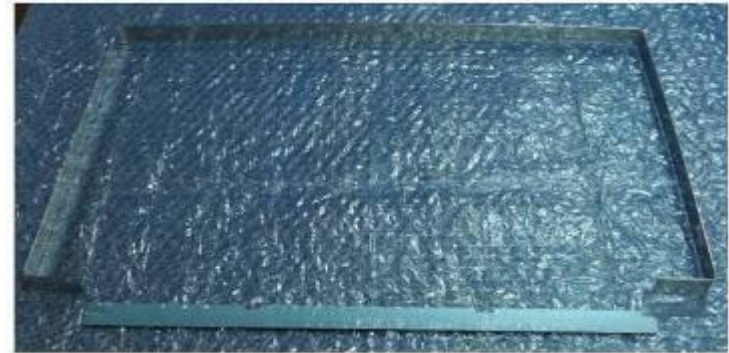
## ▶ Remove Trim Cover From Rear Cover



9.Remove Trim Cover From Rear Cover.

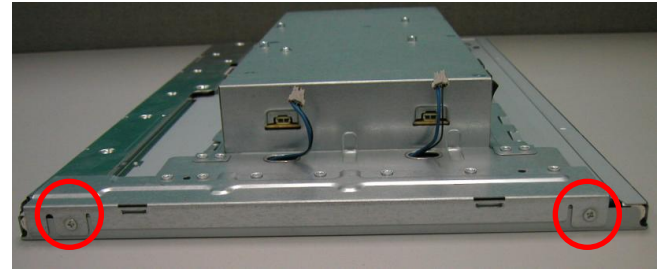
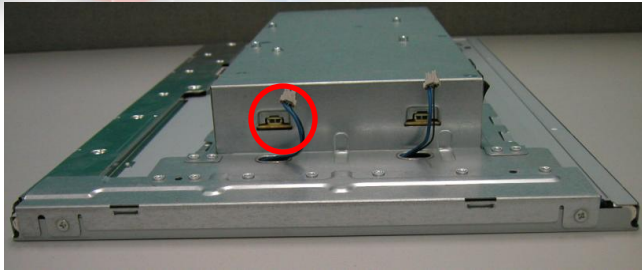


10.Dissecting To Complete.



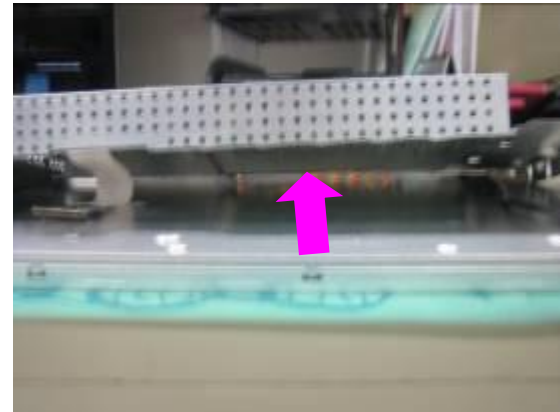
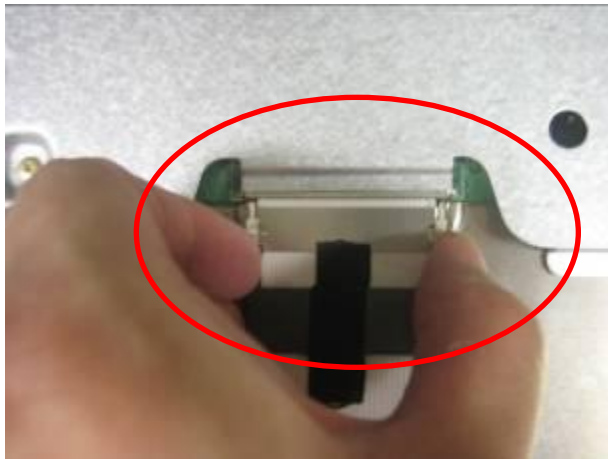


# Take Screw(\*2) Off From Chassis Cover & Remove Panel



1.Remove connector from Chassis cover.

2.Take Screw(x2) Off from Chassis cover & Remove Speaker Off From Chassis Cover.

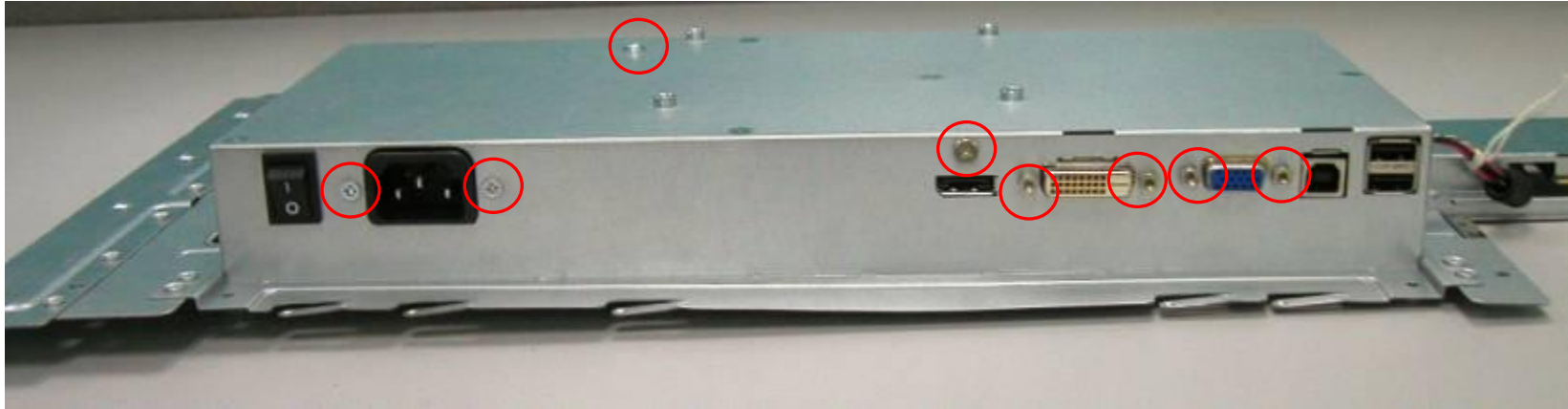


3.Remove connector off from Panel.

4.Remove the panel.



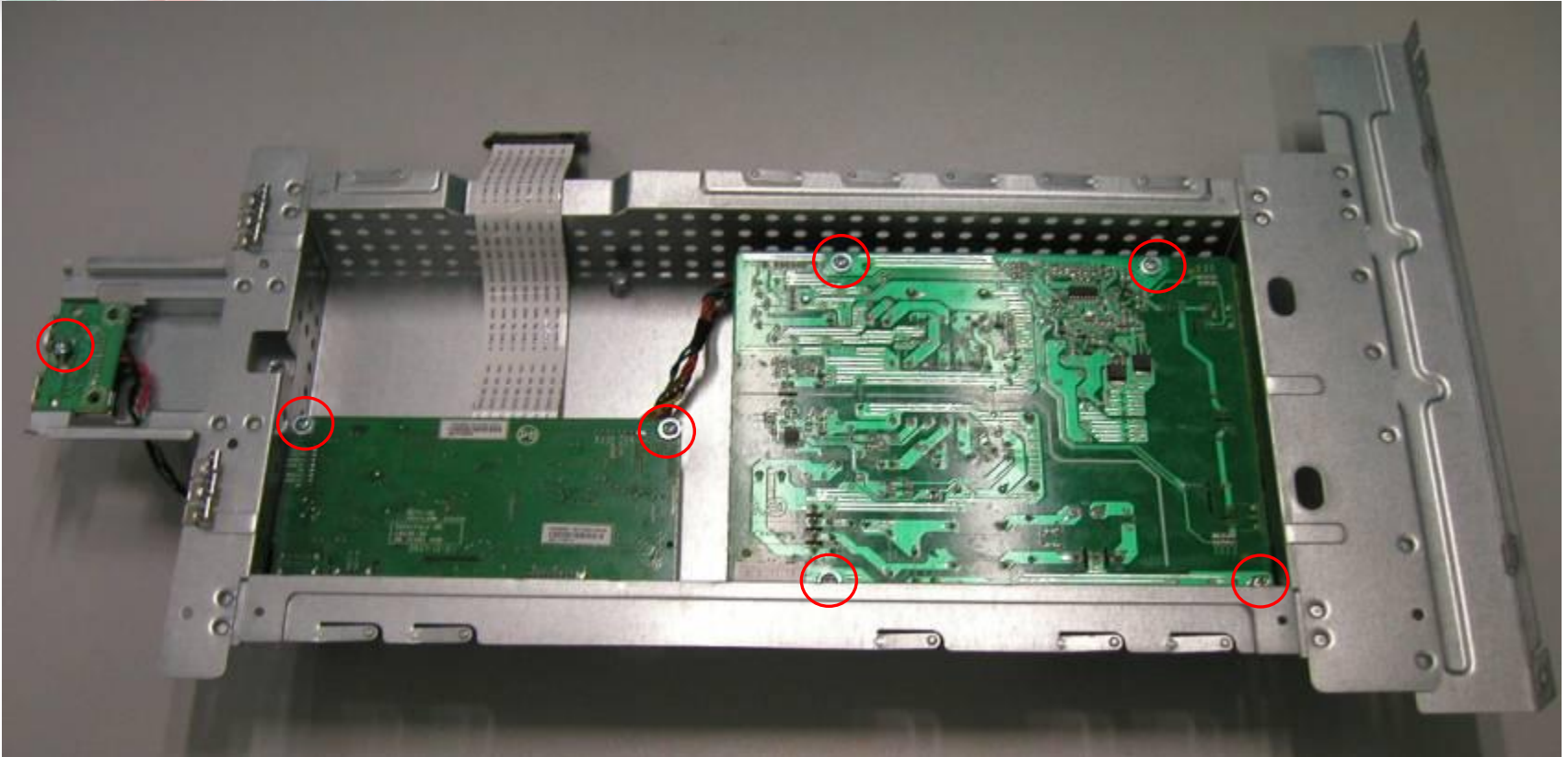
## Take Screw(x8) Off From P.C.B



1. Take Screw(x8) Off From P.C.B



## ▶ Take Screw(x7) Off From P.C.B

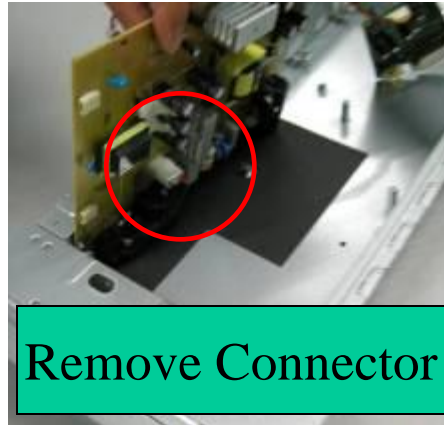




# Take Screw(x8) Off From P.C.B & Remove BKT (Printed Circuit Assemblies>10cm\*\*2)



USB BOARD



Remove Connector



Interface Board



Interface wire



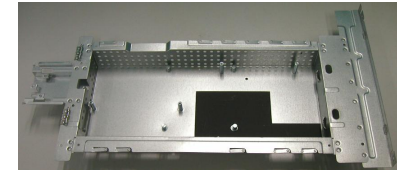
Power Board



Switch



Panel

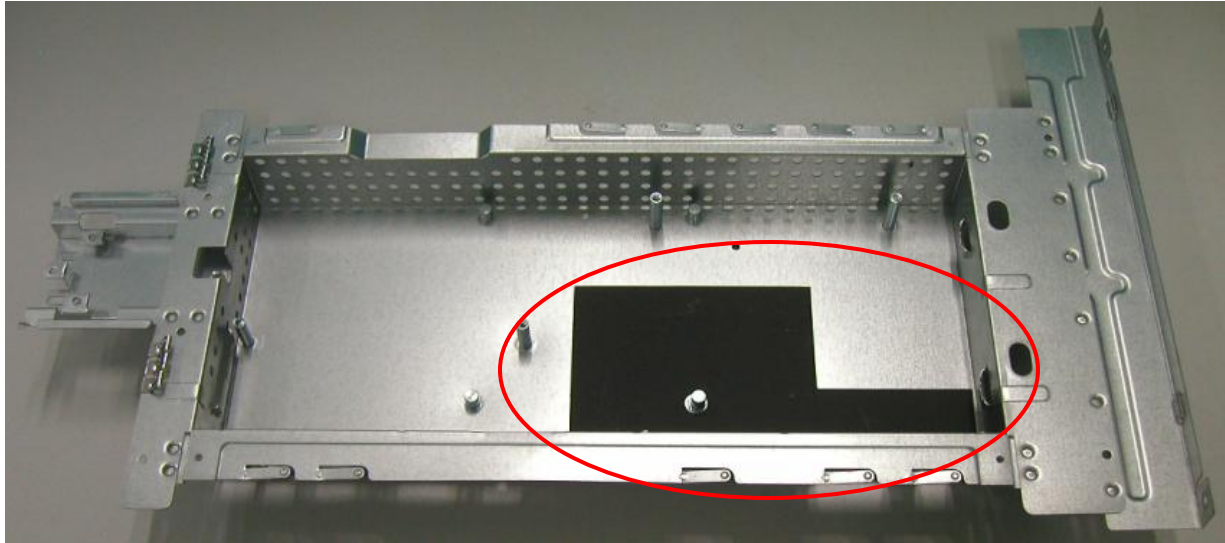


CHASSIS COVER

Dissecting to complete.

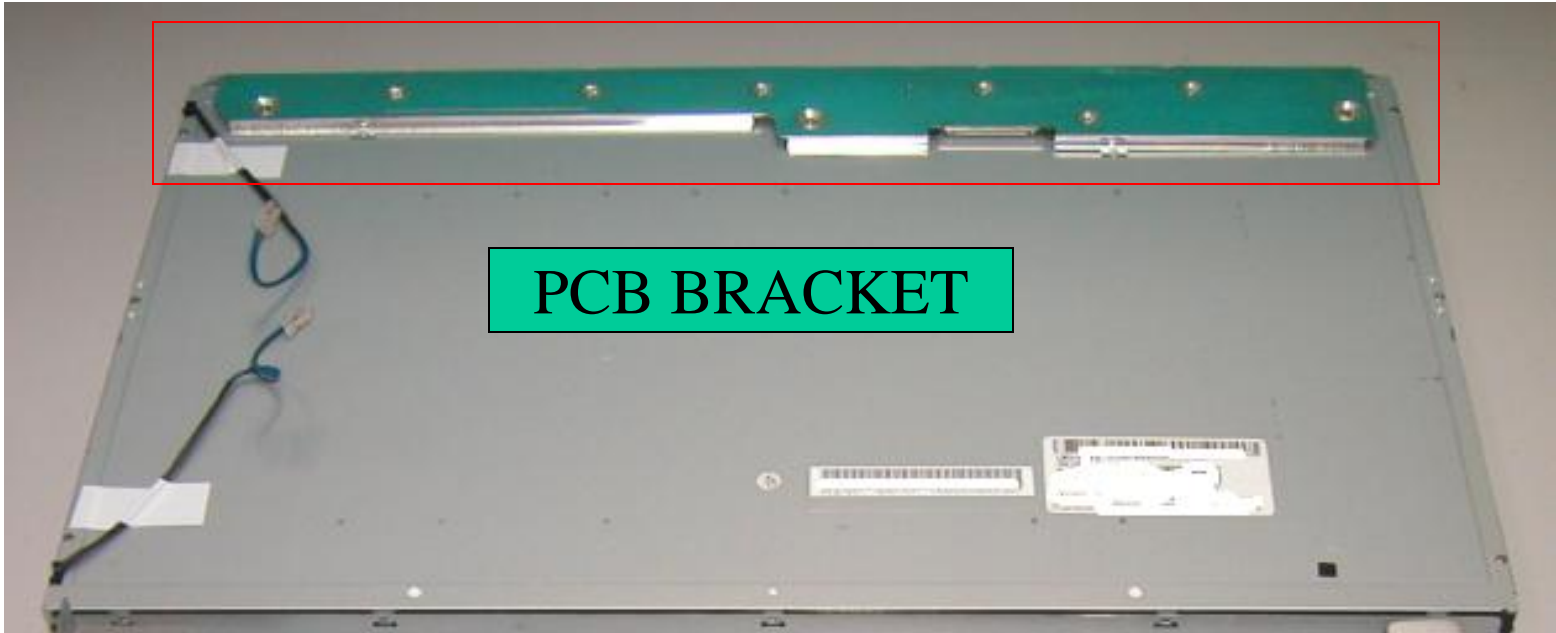


## Remove Mylar From Chassis Cover





# LCD PANEL EXPLODE







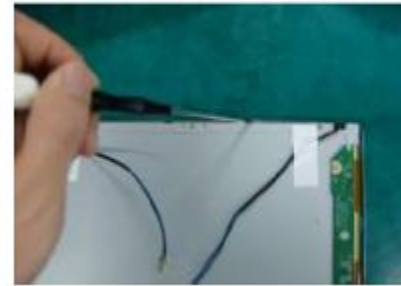
# LCD PANEL EXPLODE



Step1 : Unfix the Screw (3 Point)  
Remove the cover shield



Step2 : Dismantle the case top (down)



Step3 : Dismantle the case top (Left/right)



Step4 : Separate case top (push the case top because of damages on COF)



Step5 : Detach AL tape on board ass'y



Step6 : Separate board ass'y



# LCD PANEL EXPLODE



Step7 : Separate wires from the tape  
(2 Point)



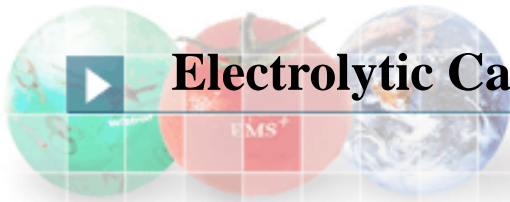
Step8 : Unfix B/L Screws(6ea)



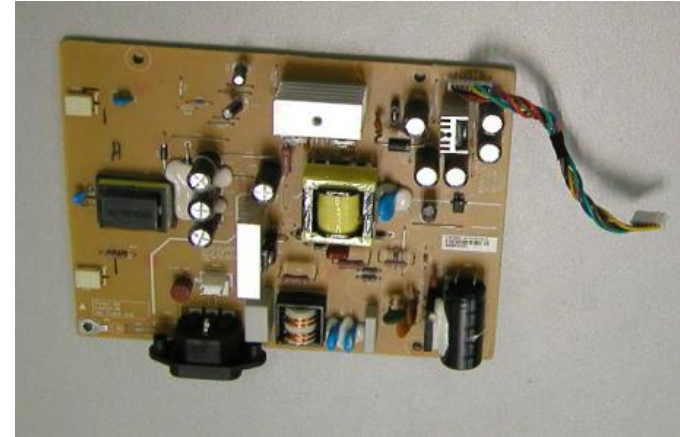
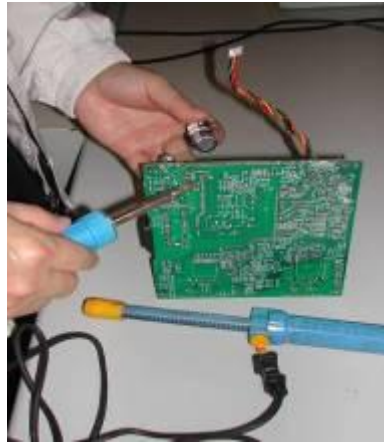
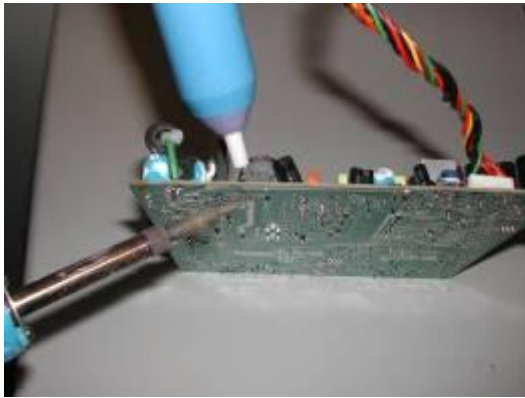
Step9 : Pull lamp housing with  
hands normal to LCM  
(\*Be careful not to break the Lamp)



Step10 : Separated lamp ass'y (UP)



# Electrolytic Capacitors Over 25mm High & Diameter Dissecting Process

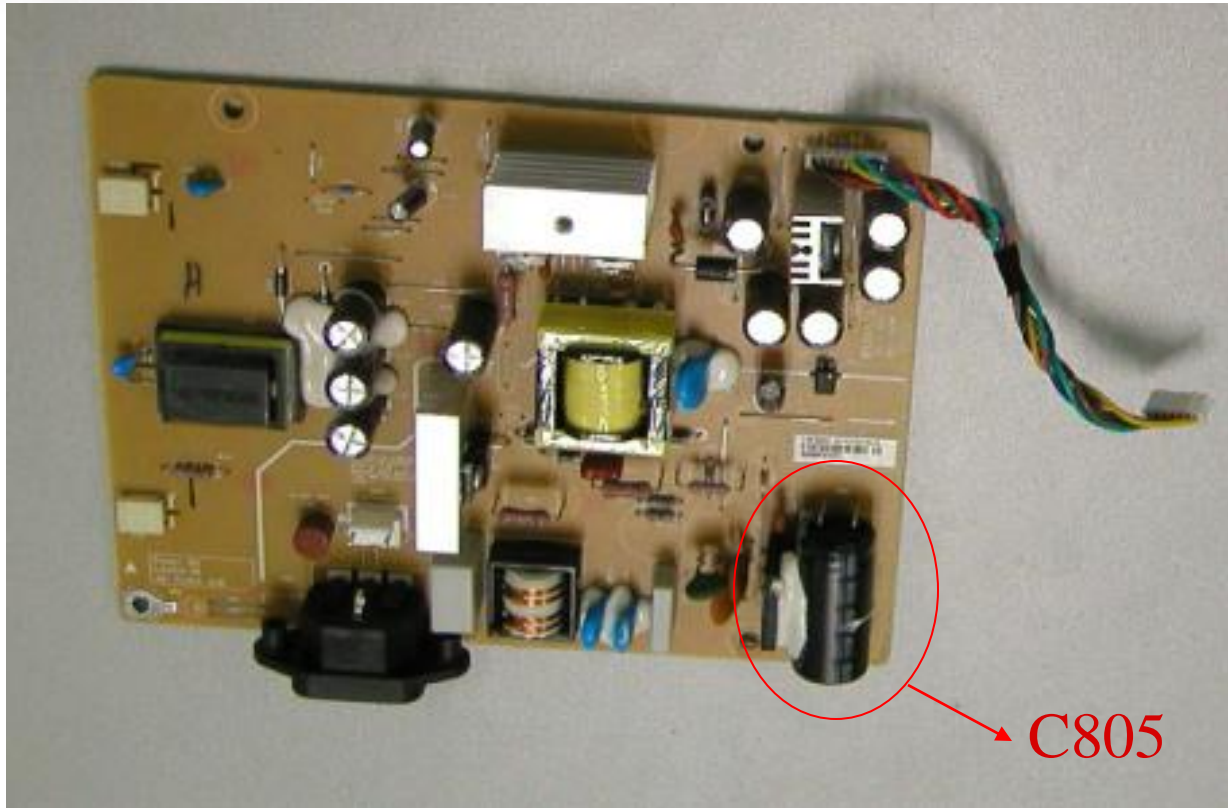


1.Heats Up, Dissolved Tin Lead.

2.Takes Down The Capacitor.

3.Dissecting To Complete.  
(Next Page Have Description)

# Electrolytic Capacitors Process Drawing



## Take Screw(\*4)Off From Quick Release



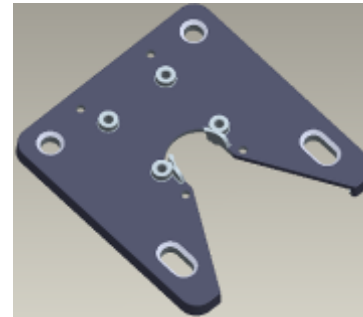
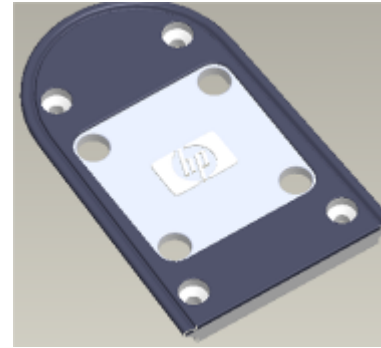


## Remove Quick Release off Stand Base





# Explode Quick Release





## Remove Cable Cover Off Stand Base





## Remove Stand Front Cover Off Stand Base



## Remove Stand Rear Cover Off Stand Base

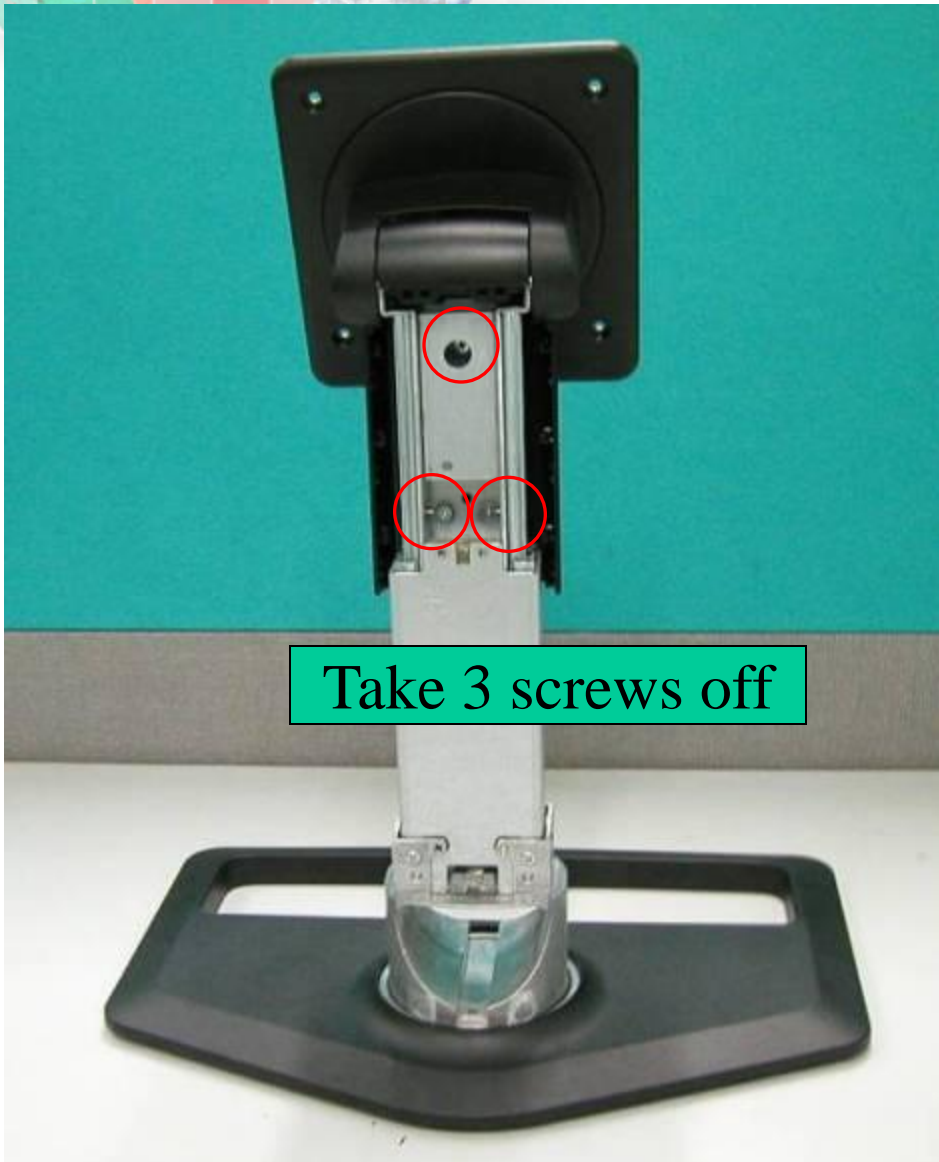




# Remove Stand Column Rear off Stand Base



## ▶ Remove Stand Column Front Off Stand BKT



## Remove Vesa Cover Assy Off Stand BKT





## Remove Vesa Cover Off VESA BKT

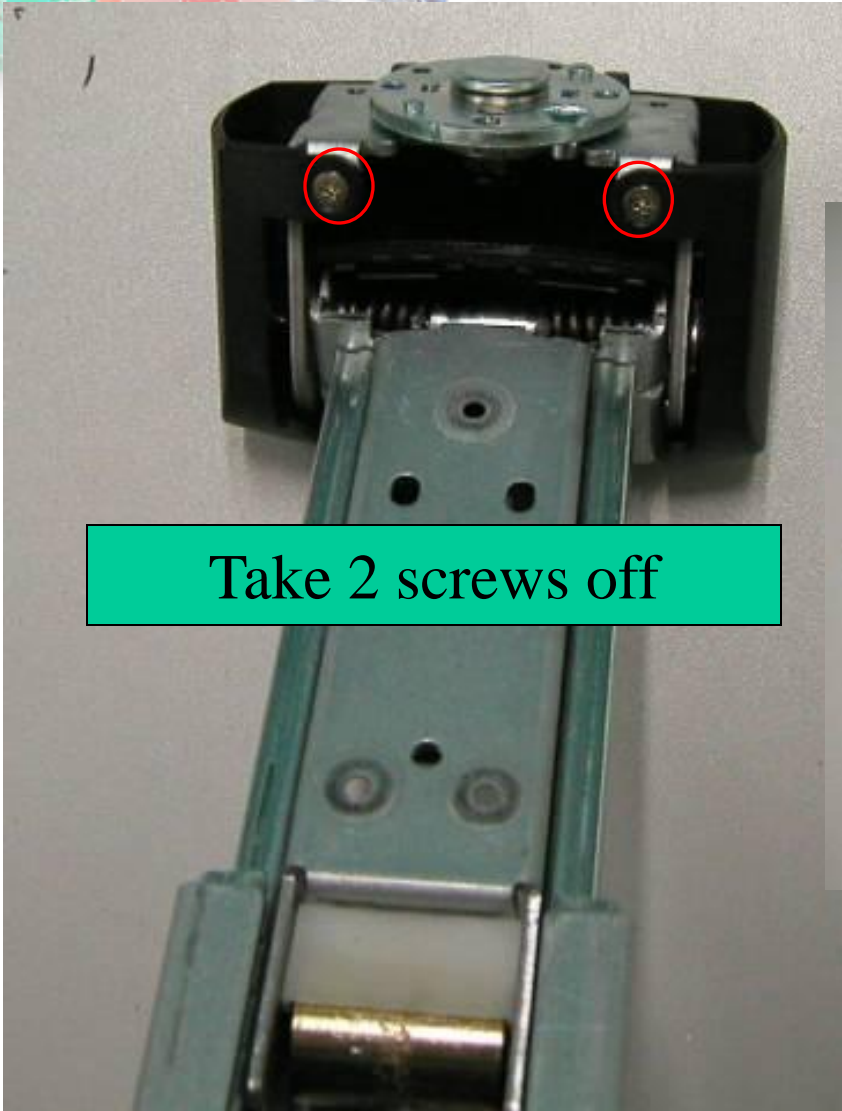


1. Use tool, Let the rubber melt, And Remove VESA Cover.

## Remove Pivot Cover Off Swivel



# Remove Tilt Cover and Stand Columnb Top Off Stand BKT



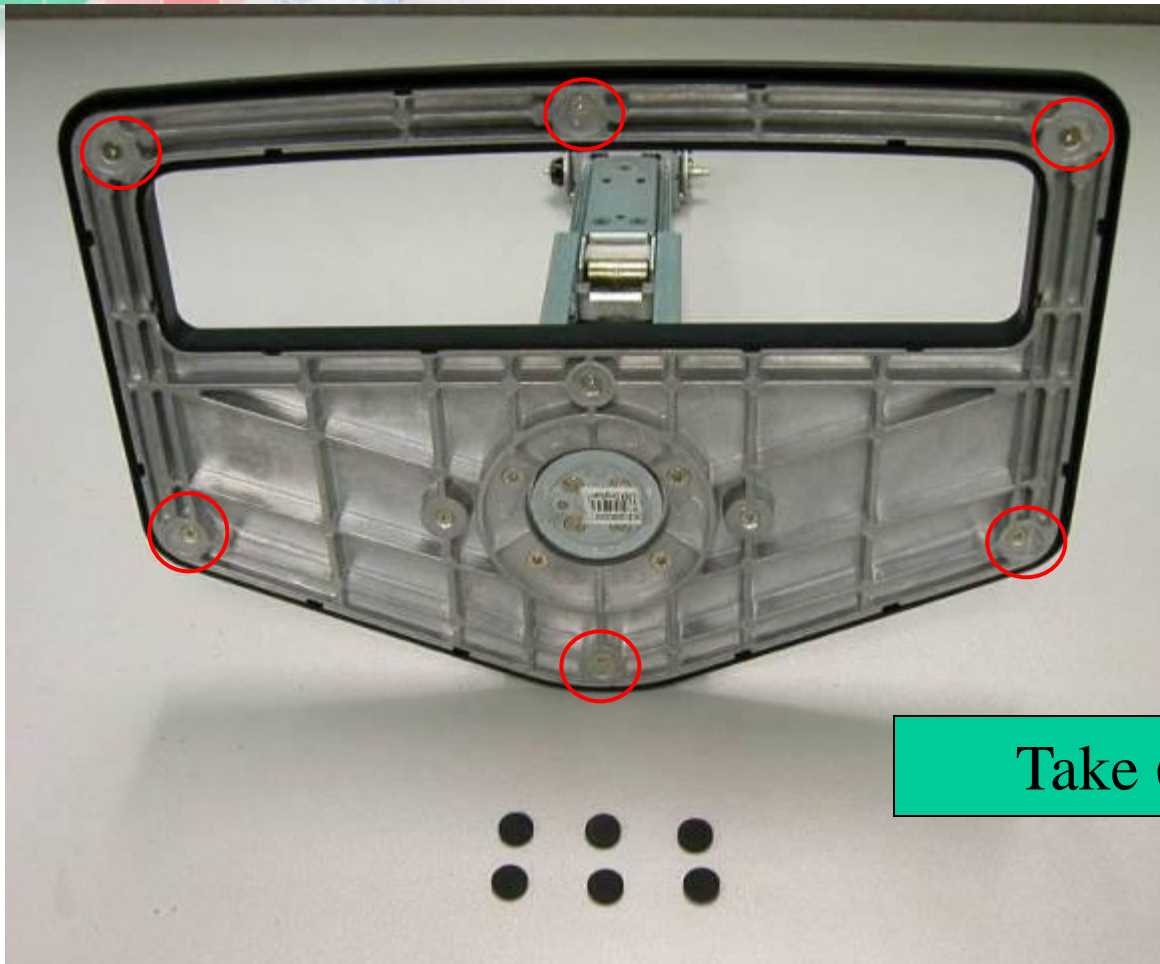
Take 2 screws off







# Remove Rubber Off Base BKT



Take 6 screws off



# Remove Base Off Base BKT





## Remove Release Button Off Stand Rear Cover

